

# HSU227

Silicon Schottky Barrier Diode for High Speed Switching

# HITACHI

ADE-208-779(Z)

Rev 0

Mar. 1999

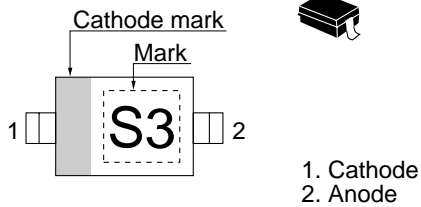
## Features

- Low capacitance. ( $C=3.0\text{pF}$  max)
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HSU227	S3	URP

## Outline



**Absolute Maximum Ratings (Ta = 25°C)**

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	25	V
Average rectified current	$I_o$	50	mA
Non-Repetitive peak forward surge current	$I_{FSM}^{*2}$	200	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. 10msec sine wave 1 pulse

**Electrical Characteristics (Ta = 25°C)**

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	0.29	0.35	V	$I_F = 1mA$
Reverse current	$I_R$	—	0.3	2.0	$\mu A$	$V_R = 20V$
Capacitance	C	—	2.45	3.0	pF	$V_R = 1V, 1=1MHz$

Main Characteristic

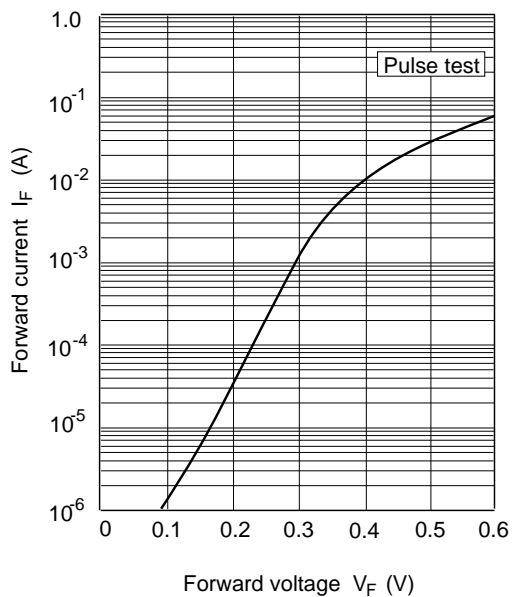


Fig.1 Forward current Vs. Forward voltage

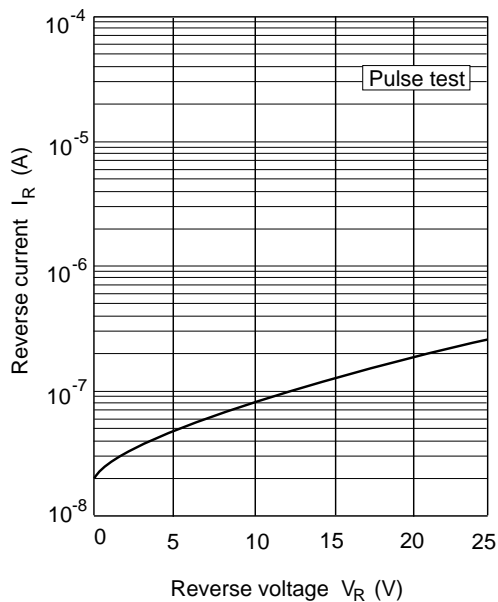


Fig.2 Reverse current Vs. Reverse voltage

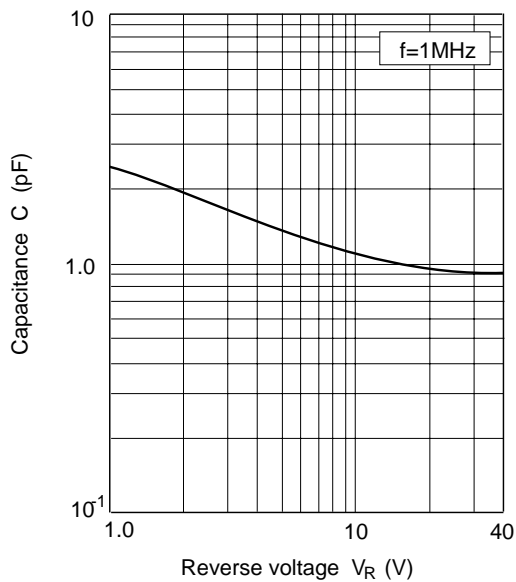
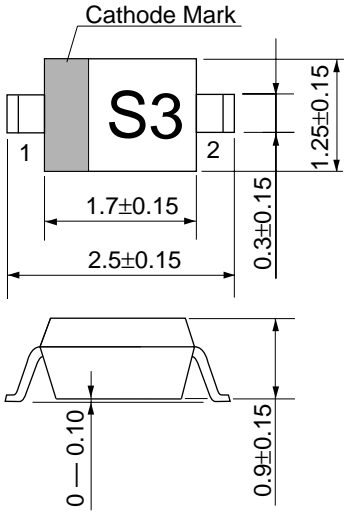


Fig.2 Capacitance Vs. Reverse voltage

Package Dimensions

Unit : mm



- 1. Cathode
- 2. Anode

Hitachi Code	URP
JEDECCode	—
EIAJCode	—
Weight(g)	0.004

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